#### 10.2mm (0.4INCH) THREE DIGIT NUMERIC DISPLAY

Part Number: BC04-11SURKWA

Hyper Red

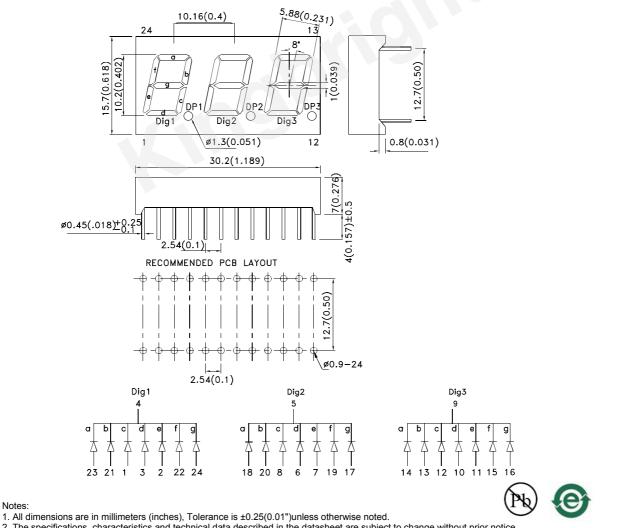
#### **Features**

- 0.4 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

#### Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

### Package Dimensions& Internal Circuit Diagram



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Selection Guide									
Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description				
			Min.	Тур.	-				
BC04-11SURKWA	Hyper Red (AlGaInP)	White Diffused	21000	56000	Common Cathode				
			*9000	*16000					

Note:

1. Luminous intensity/ luminous Flux: +/-15%. \* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	645		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I⊧=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	I⊧=20mA
IR	Reverse Current	Hyper Red		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

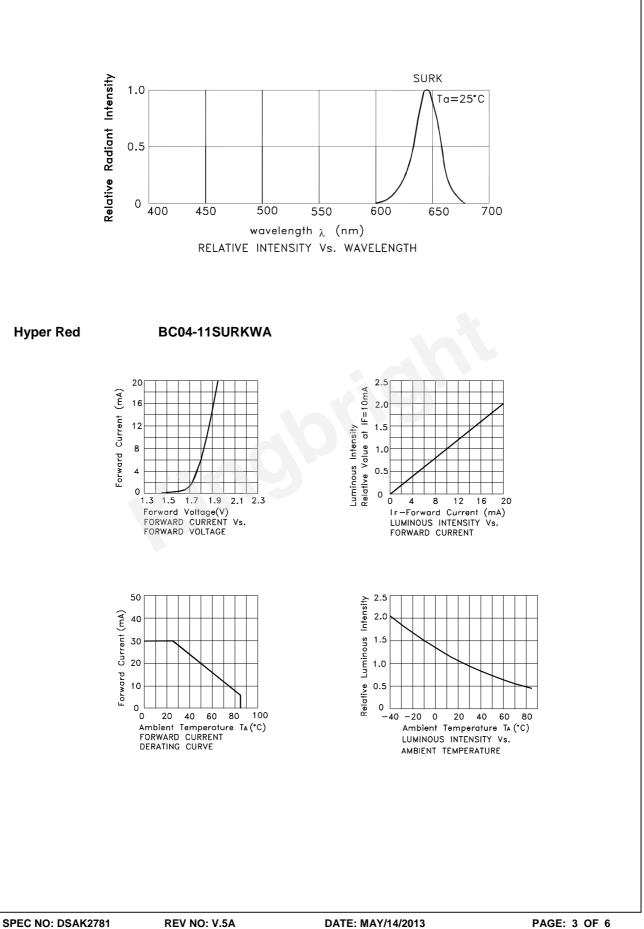
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

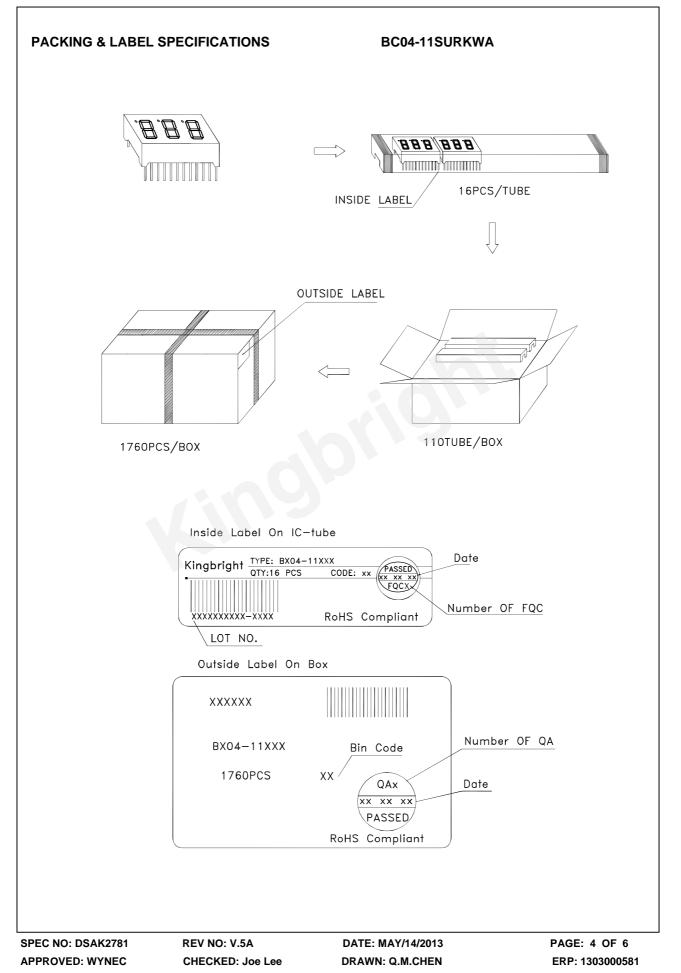
#### Absolute Maximum Ratings at TA=25°C

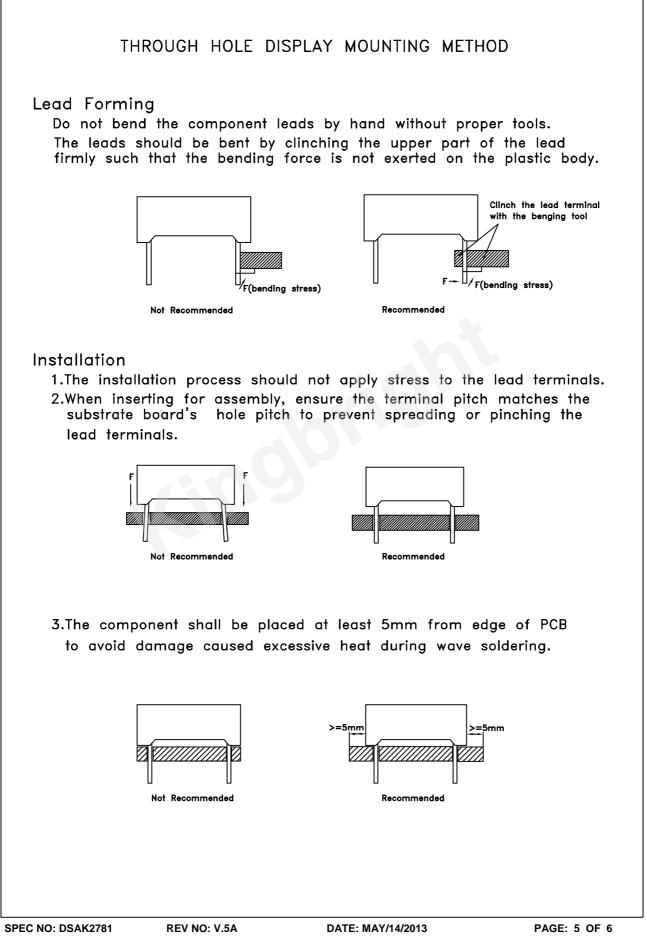
Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	260°C For 3-5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

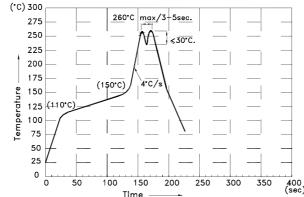






### DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



#### NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.

2.Do not apply stress on epoxy resins when temperature is over 85°C.

3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).

4.During wave soldering , the PCB top-surface temperature should be kept below 105°C 5.No more than once.

### Soldering General Notes:

- 1. Through-hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

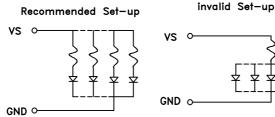
### CLEANING

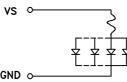
1.Mild "no-clean" fluxes are recommended for use in soldering.

2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

1.Protective current-limiting resistors may be necessary to operate the Displays. 2.LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.





Detailed application notes are listed on our website. http://www.kingbright.com/application notes

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